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Product Change Notification - JAON-14ZGDV728

(Printer Friendly)

Date: 19 Jul 2016

Product Memory; Analog (Linear & Mixed Signal) AND Interface

Category:

Notification CCB 2701 Initial Notice: Qualification of palladium coated

subject: copper with gold flash (CuPdAu) bond wire in selected

products of the 160K wafer technology available in 8L

PDIP package at MMT assembly site

Notification

PCN Status: Initial notification

text:

Microchip Parts Affected:

Please open the attachments found in the attachments field

below labeled as PCN # Affected CPN.

NOTE: For your convenience Microchip includes identical

files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L PDIP package at MMT assembly

site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu)

bond wire

Pre and Post Change Summary:

Pre Change	Post Change

Assembly Site	MMT assembly site	MMT assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	CRM-1064L	CRM-1064L
Molding compound material	GE800	GE800
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated Qualification Completion Date: September 2016

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

		July 2016				->		September 2016				
	Workweek	27	28	29	30		35	36	37	38	39	
ſ				X								

Initial PCN Issue Date					
Qual Report Availability				X	
Final PCN Issue Date				X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

July 19, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN_JAON-14ZGDV728_Qual_Plan.pdf

PCN_JAON-14ZGDV728_Affected_CPN.pdf PCN_JAON-14ZGDV728_Affected_CPN.xls

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